

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants : Sion C. Quinlan and Tim J. Bales      Attorney Docket No.: 30022/US/3  
Filed : Concurrently herewith      Customer No. : 27,076  
Title : SEMICONDUCTOR PACKAGE ASSEMBLY AND METHOD FOR ELECTRICALLY  
ISOLATING MODULES

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**INFORMATION DISCLOSURE STATEMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In accordance with 37 C.F.R. §§ 1.56 and 1.97 through 1.98, applicant wishes to make known to the Patent and Trademark Office the references set forth on the attached form PTO-1449 (copies of the cited references, as required under 37 C.F.R. § 1.98, are enclosed). Although the aforesaid references are made known to the Patent and Trademark Office in compliance with applicant's duty to disclose all information he is aware of which is believed relevant to the examination of the above-identified application, applicant believes that his invention is patentable.

Please acknowledge receipt of this Information Disclosure Statement and kindly make the cited references of record in the above-identified application.

Respectfully submitted,  
DORSEY & WHITNEY LLP



Steven H. Arterberry  
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Enclosures:

Postcard

Form PTO-1449

Cited References (36)

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FORM PTO-1449 (REV.7-80)	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY. DOCKET NO. 30022/US/3	APPLICATION NO. Not Yet Assigned
<b>INFORMATION DISCLOSURE STATEMENT</b> <i>(Use several sheets if necessary)</i>		APPLICANT(S) Sion C. Quinlan and Tim J. Bales	
		FILING DATE Concurrently herewith	GROUP ART UNIT not yet assigned

### U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	AA	5,975,958	11-02-99	Weidler	439	620	
	AB	6,023,202	02-08-00	Hill	333	24	
	AC	6,109,971	08-29-00	Vadlakonda	439	620	
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	AG	6,021,499	02/01/00	Aleshi	713	300	

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							YES	NO
	AH	00/45420	08/03/00	WO				
	AI	0 801 468 A2	10/15/97	EP				

### OTHER PRIOR ART *(Including Author, Title, Date, Pertinent Pages, Etc.)*

	AJ	Al-sarawi, Said F., "Wire Bonded Stacked Chips," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website "http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node35," January 25, 2002, pp. 1-2
	AK	Al-sarawi, Said F., "Blind Castellation Interconnection," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website "http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node44," January 25, 2002, p. 1
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	AQ	Al-sarawi, Said F., "Interconnect Capacity," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website "http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node26," January 25, 2002, pp. 1-2					
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	AS	Al-sarawi, Said F., "Stacked Tape Carrier," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website <a href="http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node30">http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node30</a> ," January 25, 2002, p. 1					
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	AX	Al-sarawi, Said F., "Area Interconnection Between Stacked ICs," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website <a href="http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node36">http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node36</a> ," January 25, 2002, p. 1					
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	BB	Agere Systems – About 1394, "1394 – The High-Speed Serial Interface for All the Right Reasons/1394 Driver Support," obtained from website <a href="http://www.agree.com/1394/about.html">http://www.agree.com/1394/about.html</a> ," January 25, 2002, p. 1		
	BC	Press Release Tuesday October 17, 2000, "Lucent Technologies introduces low-power IEEE-1394A chip for high-speed connection between PCs and consumer electronic devices," obtained from website <a href="http://www.lucent.com/press/1000/001017.mea.html">http://www.lucent.com/press/1000/001017.mea.html</a> ," January 25, 2002, pp. 1-3		
	BD	1394 Trade Association: Technology, "1394 Technology," obtained from website <a href="http://www.1394ta.org/Technology/">http://www.1394ta.org/Technology/</a> ," January 25, 2002, p. 1		
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	BF	Apple Computer, Inc., "Firewire Technology Fact Sheet," obtained at website "http://a772.g.akamai.net/7/772/51/f7f756ae8e5bf0/www.apple.com/firewire/pdf/FireWireFS-b.pdf", March 13, 2002, pp. 1-4		
	BG	McMunn, Lee James, "The Physical Layer," obtained at website "http://www.awstevenson.demon.co.uk/SYSNOTES/physic.htm," March 12, 2002, pp. 1-2		
	BH	Willis, P. J., "Communication Protocols," obtained at website "http://www.maths.bath.ac.uk/~pjw/NOTES/networks/chapter2_6.html," August 17, 2001, p. 1		
	BI	Willis, P. J., "The OSI Model," obtained at website "http://www.maths.bath.ac.uk/~pjw/NOTES/networks/sections2_6_1.html," August 17, 2001, p.1		
	BJ	Willis, P. J., "Physical Layer," obtained at website "http://www.maths.bath.ac.uk/~pjw/NOTES/networks/subsection2_6_1_1.html," August 17, 2001, p. 1		
	BK	Willis, P. J., "Data Link Layer," obtained at website "http://www.maths.bath.ac.uk/~pjw/NOTES/networks/subsection2_6_1_2.html," August 17, 2001, p.1		
	BL	Willis, P. J., "Network Layer," obtained at website "http://www.maths.bath.ac.uk/~pjw/NOTES/networks/subsection2_6_1_3.html," August 17, 2001, p.1		
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	BO	Embedded Systems Programming, "Fundamentals of Firewire," obtained at website "http://www.embedded.com/1999/9906/9906feat2.htm," August 28, 2001, pp. 1-14			
	BP	Microprocessor and Microcomputer Standards Committee of the IEEE Computer Society, "P1394a Draft Standard for a High Performance Serial Bus (Supplement)," The Institute of Electrical and Electronics Engineers, Inc., June 30, 1999, pp.1-27			
	BQ	Lucent Technologies, Inc., "IEEE 1394 Isolation," Application Note, November 1998, obtained at website "http://www.agere.com/1394/docs/AP98074-01.pdf," pp. 1-16			
EXAMINER			DATE CONSIDERED		
<b>* EXAMINER:</b> Initial if reference considered, whether or not criteria is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant(s).					